



<b>Title of Change:</b>	Transfer of the Manufacturing of QFN28 5X5 Assembly Devices from SPEL Semiconductor Limit to UTAC Thai Limited Site 3 for Wireless Connectivity Solutions Products.	
<b>Proposed first ship date:</b>	27 September 2018 or earlier after customer approval.	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Peter.Vo@onsemi.com>	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Phine.Guevarra@onsemi.com>	
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>	
<b>Change Part Identification:</b>	Affected parts are marked with the manufacturing site code, "G", for UTAC Thai Limited.	
<b>Change Category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
<b>Sites Affected:</b>	ON Semiconductor Sites: None	External Foundry/Subcon Sites: UTAC
<b>Description and Purpose:</b>		
This final product change notification is to inform the assembly manufacturing transfer of the affected parts of package type QFN28 5X5 for Wireless Connectivity Solutions products from SPEL Semiconductor Limit to UTAC Thai Limited Site 3. This change is to allow better management of the supply chain to meet customers' demands. With the transfer, the BOM is changing from SPEL to UTAC, and the BOM at UTAC are standard material. There is no product marking change as a result of this change.		
	<b>Before Change Description</b>	<b>After Change Description</b>
Site	SPEL	UTAC Thailand Site 3
Epoxy	CRM-1076NS	8600
Wire	0.8MIL Au	0.7MIL Au
Mold	CEL-9220ZHF10L	G700LTD



**Reliability Data Summary:**

Based on similarity on below device previously qualified at UTAC Thailand.

**QV DEVICE NAME:** AX8052F143-3-TX30

**RMS:**

**PACKAGE:** QFN 40 7X5

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/480
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/45

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted by this change.

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
AX5043-1-TA05	AX8052F143-3-TX30
AX5043-1-TW30	
AX5051-1-TA05	
AX5051-1-TW30	